

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT7685269

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ZVI OR-BACH	09/22/2022
BRIAN CRONQUIST	09/22/2022
DEEPAK SEKAR	09/22/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MONOLITHIC 3D INC.
<b>Street Address:</b>	1662 COVE POINT RD
<b>City:</b>	KLAMATH FALLS
<b>State/Country:</b>	OREGON
<b>Postal Code:</b>	97601
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17951545
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	4088399533
<b>Email:</b>	Brian@Monolith3D.com
<b>Correspondent Name:</b>	BRIAN CRONQUIST
<b>Address Line 1:</b>	1662 COVE POINT RD
<b>Address Line 4:</b>	KLAMATH FALLS, OREGON 97601
<b>ATTORNEY DOCKET NUMBER:</b>	M3D_C-ISCON4
<b>NAME OF SUBMITTER:</b>	BRIAN CRONQUIST
<b>SIGNATURE:</b>	/briancronquist/
<b>DATE SIGNED:</b>	12/08/2022
<b>Total Attachments: 3</b>	
source=M3D_C-IScon4_Assignment_Zvi---signed#page1.tif	
source=M3D_C-IScon4_Assignment_Deepak---signed#page1.tif	
source=M3D_C-IScon4_Assignment_Brian---signed#page1.tif	

**ASSIGNMENT**

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in Haifa, Israel;** have made a certain invention, and executed United States Patent Application entitled:

**A MULTILEVEL SEMICONDUCTOR DEVICE AND STRUCTURE WITH  
IMAGE SENSORS AND WAFER BONDING**

as described in US Application Serial No. 17/tbd and filed on or about September 23, 2022; and

Whereas, Monolithic 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

DATE on 09 / 22 / 2022

Zvi

First Name

po. 1/c '23

Middle Initial

Or-Bach

Last Name

**PATENT**

REEL: 062033 FRAME: 0732 530e7ac9

**ASSIGNMENT**

Whereas, I, **Deepak Sekar (hereinafter referred to as Assignor(s)), residing in Sunnyvale, California;** have made a certain invention, and executed United States Patent Application entitled:

**A MULTILEVEL SEMICONDUCTOR DEVICE AND STRUCTURE WITH  
IMAGE SENSORS AND WAFER BONDING**

as described in U.S. Application Serial No. 17/tbd filed on or about September 23, 2022; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

**DATE** on 09 / 22 / 2022

**(Deepak**

First Name

*Deepak C. Sekar*

Middle Initial

**Sekar)**

Last Name

**PATENT**

□ **REEL: 062033 FRAME: 0733** 33bff991

**ASSIGNMENT**

Whereas, I, **Brian Cronquist (hereinafter referred to as Assignor(s)), residing in Klamath Falls, Oregon;** have made a certain invention, and executed United States Patent Application entitled:

**A MULTILEVEL SEMICONDUCTOR DEVICE AND STRUCTURE WITH  
IMAGE SENSORS AND WAFER BONDING**

as described in US Application Serial No. 17/tbd filed on or about September 23, 2022; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged, I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

*Brian Cronquist*

**DATE** on 09 / 22 / 2022

**(Brian**

**Cronquist)**

First Name

Middle Initial

Last Name